

Title (en)

Etching method for processing substrate, dry etching method for polyetheramide resin layer, production method of ink-jet printing head, ink-jet head and ink-jet printing apparatus

Title (de)

Ätzverfahren zur Behandlung eines Substrates, Trockenätzverfahren für eine Polyetheramid-Harzschicht, Herstellungsverfahren für einen Tintenstrahl-Druckkopf, Tintenstrahlkopf und Tintenstrahl-Druckvorrichtung

Title (fr)

Procédé de gravure pour le traitement d'un substrat, procédé de gravure sèche pour couche de résine polyéthéramide, procédé de production d'une tête d'impression à jet d'encre, tête à jet d'encre et dispositif d'impression à jet d'encre

Publication

EP 0964440 B8 20110216 (EN)

Application

EP 99111440 A 19990611

Priority

JP 16394098 A 19980611

Abstract (en)

[origin: EP0964440A2] An ink-jet head is produced by means of an etching employing a mask member which is formed without defects such as pinholes. More specifically, a polyetheramide resin layer is employed as an etching-resistance mask (3) when processing a substrate (1) by means of the etching, in which the polyetheramide resin layer is etched by means of an etching gas containing oxygen as main component. <IMAGE>

IPC 8 full level

H01L 21/027 (2006.01); **B41J 2/16** (2006.01); **H01L 21/308** (2006.01); **H01L 21/311** (2006.01)

CPC (source: EP US)

B41J 2/1604 (2013.01 - EP US); **B41J 2/1628** (2013.01 - EP US); **B41J 2/1629** (2013.01 - EP US); **B41J 2/1631** (2013.01 - EP US); **B41J 2/1645** (2013.01 - EP US)

Cited by

CN1107592C; CN1109604C; KR100733939B1; RU2672034C1; US7429335B2; US7063933B2; WO2004111732A1

Designated contracting state (EPC)

DE ES FR GB IT NL

DOCDB simple family (publication)

EP 0964440 A2 19991215; **EP 0964440 A3 20000524**; **EP 0964440 B1 20100818**; **EP 0964440 B8 20110216**; DE 69942682 D1 20100930; US 6379571 B1 20020430

DOCDB simple family (application)

EP 99111440 A 19990611; DE 69942682 T 19990611; US 32935799 A 19990610